**European Hybrid IBIS Summit with IEEE SPI 2024**

May 15, 2024

**Agenda**

All times WEST (UTC +1)

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| 14:00 | **SIGN IN** |
| 14:05 | **Welcome**Lance Wang (Zuken USA, USA)(Chair, IBIS Open Forum) |
| 14:10 | **IBIS Chair’s Report** Lance Wang (Zuken USA, USA)(Chair, IBIS Open Forum) |
| 14:25 | **Accurate IBIS Model for IO pads having Floating Rail ESD Architecture**Manish Bansal (STMicroelectronics, India)Mihir Pratap Singh (STMicroelectronics, India)Rahul Kumar (STMicroelectronics, India)Raushan Kumar (STMicroelectronics, India)[Presented by Manish Bansal] |
| 14:40 | **Accurate SI Analysis under Overclocking Conditions**Michael Schaeder (Zuken, Germany)Mariusz Faferko (Zuken, Germany)Markus Buecker (Zuken, Germany)[Presented by Markus Buecker] |
| 15:00 | **Impact of Port Type in S-Parameter Extraction of Package and PCB High-Speed Interconnections**Marco Occhiali (Ansys, Italy)Aurora Sanna (STMicroelectronics, Italy)Simona Cucchi (STMicroelectronics, Italy)[Presented by Marco Occhiali] |
| 15:20 | **USB 3.0 IBIS-AMI Model Construction Based on Measurement and Neural Network**Jiahuan Huang (MST EMC Lab, USA)Joonho Joo (MST EMC Lab, USA)Hank Lin (ASUS, Taiwan)Bin-Chyi Tseng (ASUS, Taiwan)Will Chan (ASUS, Taiwan)Chulsoon Hwang (MST EMC Lab, USA)[Presented by Jiahuan Huang] |
| 15:40 | **Update on BIRD226: PSIJ Sensitivity**Kinger Cai (Intel, USA)Fern Nee Tan (Intel, Malaysia)Chi-te Chen (Intel, USA)Michael Mirmak (Intel, USA)[Presented by Kinger Cai] |
| 16:00 | **BREAK (15 minutes)** |
| 16:15 | **Update on BIRD223.1: Add Support for SPIM in IBIS**Kinger Cai (Intel, USA)Chi-te Chen (Intel, USA)[Presented by Kinger Cai] |
| 16:45 | **Pole-Residue Data Format for Touchstone** Arpad Muranyi (Siemens EDA, USA) |
| 17:10 | **Priorities and Alternatives for Touchstone 3.0 Port Mapping**Michael Mirmak (Intel Corp., USA) |
| 17:25 | **OPEN DISCUSSION** |
| 17:40 | **CLOSING REMARKS** - Next IBIS Open Forum Meeting Friday, May 12, 2023 |
| 17:45 | **END OF SUMMIT**  |
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